L Number	Hits	Search Text	DB	Time stamp
1	0	microcircuit and stacked and encapsulant	USPAT;	2003/03/12
•		and encasing and removing near insulation	US-PGPUB;	12:16
			EPO; JPO;	12.10
			DERWENT;	
			IBM_TDB	
2	0	microcircuit and stacked and encapsulant	USPAT;	2003/03/12
_		and removing near insulation	US-PGPUB;	12:17
		and removing near madazion	EPO; JPO;	12.17
			DERWENT;	
			IBM_TDB	
3	0	microcircuit and PEM and encapsulant and	USPAT;	2003/03/12
J	•	removing near insulation	US-PGPUB;	12:17
		Telliovilly lical illoulation	EPO; JPO;	12.17
			DERWENT;	
			IBM_TDB	
4	0	PEM and encapsulant and removing near	USPAT;	2003/03/12
4		insulation	US-PGPUB;	12:17
		insulation	1	12:17
			EPO; JPO;	
			DERWENT;	
_			IBM_TDB	2002/02/42
5	0	PEM and removing near insulation	USPAT;	2003/03/12
			US-PGPUB;	12:17
			EPO; JPO;	
			DERWENT;	
_			IBM_TDB	0000/00/40
6	2601	PEM	USPAT;	2003/03/12
			US-PGPUB;	12:17
	i		EPO; JPO;	
			DERWENT;	
_			IBM_TDB	
7	80	(PEM) and encapsulation	USPAT;	2003/03/12
			US-PGPUB;	12:18
			EPO; JPO;	
			DERWENT;	
_			IBM_TDB	0000100110
8	29	(PEM) and encapsulation and removing	USPAT;	2003/03/12
		•	US-PGPUB;	12:18
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
9	394917	(PEM) and removing insulation	USPAT;	2003/03/12
			US-PGPUB;	12:20
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
10	0	(PEM) and removing near insulation	USPAT;	2003/03/12
			US-PGPUB;	12:20
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	,

44	0	(PEM) and removing near encapsulant	USPAT;	2003/03/12
11	U	(PEM) and removing near encapsulant	US-PGPUB:	2003/03/12 12:21
			,	12:21
			EPO; JPO;	
			DERWENT;	
		·	IBM_TDB	
12	2	(PEM) and removing same encapsulant	USPAT;	2003/03/12
			US-PGPUB;	12:30
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
13	o	20020119605.URPN.	USPAT	2003/03/12
				12:22
14	21	("4017495" "4118861" "4490496"	USPAT	2003/03/12
14	21	, , , , , , , , , , , , , , , , , , , ,	USFAT	12:22
		"4729062" "4826756" "4830922"		12:22
		"4902769" "4920639" "4991286"		
		"5274913" "5381304" "5405807"		
		"5434751" "5512613" "5560934"		
		"5600181" "5641546" "5685071"		
		"5828126" "5858943" "6111323").PN.		
15	41	("3801880" "3864426" "4012832"	USPAT	2003/03/12
		"4370292" "4529755" "4604444"		12:24
		"4626556" "4632798" "4663190"		
		"4729062" "4738892" "4983683"		
		"4985751" "5037779" "5043211"		
		"5061657" "5064895" "5072874"		
		"5120678" "5128204" "5140068"		
		"5160786" "5199163" "5250848"		
		"5264520" "5274913" "5286572"		
		"5298548" "5300625" "5313365"		
		"5326413" "5371328" "5381304"		
		"5434751" "5457149" "5460767"		
		"5471096" "5474620" "5498689"		
		"5821456" "5863664").PN.		
16	0	(PEM) and removing and grinding near	USPAT;	2003/03/12
		encapsulant	US-PGPUB;	12:31
		· ·	EPO; JPO;	
			DERWENT:	
			IBM_TDB	
17	o	(PEM) and removing and grinding near	USPAT;	2003/03/12
• *		(encapsulant or insulation)	US-PGPUB;	12:32
		(encapsulant of insulation)	1	12.02
			EPO; JPO;	
			DERWENT;	
	_		IBM_TDB	0000/00/45
18	6	removing and grinding near (encapsulant or	USPAT;	2003/03/12
		insulation)	US-PGPUB;	12:33
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
19	1	IC and grinding near (encapsulant or	USPAT;	2003/03/12
		insulation)	US-PGPUB;	12:36
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
	<u> </u>		IDM_IDD	<u>. </u>

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20	0	8153696.URPN.	USPAT	2003/03/12
				12:34
21	1	1996-331608.NRAN.	DERWENT	2003/03/12
				12:34
22	552166	29/\$.ccls. grinding near encapsulant or	USPAT;	2003/03/12
		insulation	US-PGPUB;	12:36
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
23	166292	29/\$.ccls. grinding near (encapsulant or	USPAT;	2003/03/12
		insulation)	US-PGPUB;	12:37
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
24	2	29/\$.ccls. and grinding near (encapsulant	USPAT;	2003/03/12
		or insulation)	US-PGPUB;	12:37
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
25	0	"Albert et al".inv.	USPAT;	2003/03/12
			US-PGPUB;	12:38
			EPO; JPO;	
			DERWENT;	
26	20	00/040!!!!	IBM_TDB	0000100140
20	28	29/840.ccls. and microcircuit	USPAT;	2003/03/12 12:39
			US-PGPUB;	12:39
			EPO; JPO; DERWENT;	
			IBM_TDB	
27	3	29/840.ccls. and microcircuit and	USPAT;	2003/03/12
		encapsulant	US-PGPUB;	12:42
			EPO; JPO;	121-72
			DERWENT;	
			IBM_TDB	
28	0	20020126459.URPN.	USPAT	2003/03/12
				12:42
29	2	"Stackable microcircuit layer "	USPAT;	2003/03/12
		_	US-PGPUB;	12:43
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
30	1	"Stackable microcircuit " and 174/52.2.ccls.	USPAT;	2003/03/12
			US-PGPUB;	12:43
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
31	4077	"Stackable microcircuit layer "and	USPAT;	2003/03/12
		(361/743;29/830 ;29/840 ;29/841 ;361/735	US-PGPUB;	12:44
		;361/746).ccls.	EPO; JPO;	
			DERWENT;	
	<u> </u>		IBM_TDB	

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32	0	"Stackable microcircuit layer" and (361/743;29/830 ;29/840 ;29/841 ;361/735 ;361/746).ccls. and grinding and removing	USPAT; US-PGPUB; EPO; JPO;	2003/03/12 12:45
:		and encasing	DERWENT; IBM_TDB	
33	1	"Stackable microcircuit layer" and	USPAT;	2003/03/12
		(361/743;29/830 ;29/840 ;29/841 ;361/735	US-PGPUB;	12:45
		;361/746).ccls. and grinding and removing	EPO; JPO; DERWENT;	
			IBM_TDB	2003/03/12
34	1	"Stackable microcircuit layer" and	USPAT; US-PGPUB;	12:45
		(361/743;29/830 ;29/840 ;29/841 ;361/735 ;361/746).ccls. and removing	EPO; JPO;	12.43
		,30 1/1 40),0013. and removing	DERWENT;	
			IBM_TDB	
35	23	microcircuit and (361/743;29/830 ;29/840	USPAT;	2003/03/12
		;29/841 ;361/735 ;361/746).ccls. and	US-PGPUB;	12:48
		removing	EPO; JPO;	
			DERWENT;	
			IBM_TDB	
36	4	(361/743;29/830 ;29/840 ;29/841 ;361/735	USPAT;	2003/03/12
		;361/746).ccls. and encapsulant near	US-PGPUB;	13:07
		removing	EPO; JPO;	
			DERWENT;	
37	17	 ("3903590" "4466181" "4783695"	IBM_TDB USPAT	2003/03/12
31	17	(3903390 4406161 4763693 "4835704" "4878991" "4933042"	USPAI	12:52
		"5019946" "5048179" "5091769"		I Z.IJZ
		"5108825" "5139969" "5144747"		
		"5151776" "5154793" "5155068"		
		"5161093" "5255431").PN.		
38	8	("3702464" "4532419" "4603249"	USPAT	2003/03/12
		"4725924" "4774633" "4803542"		13:03
		"4822989" "4931853").PN.		
39	10	("5207864" "5386624" "5406025"	USPAT	2003/03/12
		"5483421" "5638597" "5739053"		13:05
		"5785234" "5813115" "5816478"		
40	6	"5873161").PN. ("3676745" "5323295" "5365403"	USPAT	2003/03/12
40	O	"5367439" "5467251" "5644103").PN.	USPAT	13:06
41	60	encapsulant near removal	USPAT;	2003/03/12
•			US-PGPUB;	13:10
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
42	0	20010039120.URPN.	USPAT	2003/03/12
				13:08
43	14	encapsulant near remove and pad and wire	USPAT;	2003/03/12
			US-PGPUB;	13:13
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	L

				
44	15	("4281031" "4344809" "4359360"	USPAT	2003/03/12
		"4826556" "5252179" "5254237"		13:12
		"5271798" "5321222" "5350737"		
		"5521360" "5552112" "5648038"		
		"5766496" "6011249" "6211499").PN.	LICDAT	2002/02/40
45	4	("3469053" "5268548" "5644837"	USPAT	2003/03/12 13:13
40		"5725762").PN.	HCDAT-	
46	27	encapsulant and encasing and removing and semiconductor near device	USPAT;	2003/03/12 13:19
j		and Semiconductor near device	US-PGPUB; EPO; JPO;	13:19
			DERWENT;	
	İ		IBM_TDB	
47	19	("4143456" "4264917" "4300153"	USPAT	2003/03/12
7'	15	"4358552" "4507675" "4642671"	OSIAI	13:15
		"4931852" "4961107" "5101465"		10.10
		"5173764" "5194930" "5379186"		
		"5434105" "5436203" "5450283"	:	
		"5488254" "5489538" "5489801"		
		"5866953").PN.		
48	0	encapsulant and encasing near removing	USPAT;	2003/03/12
		and semiconductor	US-PGPUB;	13:19
			EPO; JPO;	, , , , , ,
			DERWENT;	
			IBM_TDB	
49	0	encapsulant and encasing near removing	USPAT;	2003/03/12
	_		US-PGPUB;	13:19
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
50	79	encapsulant near removing	USPAT;	2003/03/12
			US-PGPUB;	13:26
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
51	11	("4460537" "4615857" "4910581"	USPAT	2003/03/12
		"5417826" "5434750" "5542171"		13:24
		"5557150" "5635671" "5656549"		
		"5780933" "5963792").PN.		
52	14	("4460537" "4615857" "4784974"	USPAT	2003/03/12
		"4910581" "5417826" "5434750"		13:25
		"5542171" "5557150" "5620928"		
		"5625235" "5635671" "5656549"		
		"5708567" "5756380").PN.		
53	0	"removing said encapsulant"	USPAT;	2003/03/12
			US-PGPUB;	13:30
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
54	0	encapsulant near grinding and	USPAT;	2003/03/12
		semiconductor near device	US-PGPUB;	13:31
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	

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55	4103	grinding and semiconductor near device	USPAT;	2003/03/12
			US-PGPUB;	13:32
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
56	10	removing and grinding and encapsulant	USPAT;	2003/03/12
		near material and semiconductor near	US-PGPUB;	13:35
		device	EPO; JPO;	
			DERWENT;	
			IBM_TDB	
57	0	20030006494.URPN.	USPAT	2003/03/12
				13:34
58	15	grinding and encapsulant near material and	USPAT;	2003/03/12
		semiconductor near device	US-PGPUB;	13:35
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
59	33	grinding and encapsulant near material and	USPAT;	2003/03/12
		semiconductor	US-PGPUB;	13:36
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
60	8	("5471087" "5773323" "5855727"	USPAT	2003/03/12
		"5863810" "5897338" "5932061"		13:39
		"6069392" "6136212").PN.		
61	23	("H001379" "3482419" "3627901"	USPAT	2003/03/12
		"3762039" "3969813" "4089704"		13:46
		"4359360" "4384917" "4474621"		
		"4567006" "4691225" "4768286"		
		"4914813" "4980019" "5041396"		
		"5138430" "5149662" "5155068"		
		"5180093" "5252179" "5398926"		
		"5406117" "5424254").PN.		
62	19	5424254.URPN.	USPAT	2003/03/12
				13:49